BTA41 A/B BTB41 B

STANDARD TRIACS

FEATURES

■ HIGH SURGE CURRENT CAPABILITY

■ COMMUTATION: (dV/dt)c>10V/µs

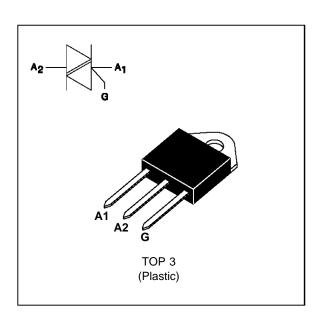
■ BTA Family:

INSULATING VOLTAGE = 2500V_(RMS)

(UL RECOGNIZED : E81734)

DESCRIPTION

The BTA41 A/B / BTB41 B triac family are high performance glass passivated PNPN devices. These parts are suitables for general purpose applications where high surge current capability is required. Application such as phase control and static switching on inductive or resistive load.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit		
I _{T(RMS)}	RMS on-state current BTA		Tc = 75 °C	40	Α
	(360° conduction angle)	втв	Tc = 85 °C	45	
ITSM	ITSM Non repetitive surge peak on-state current (Tj initial = 25°C)			315	Α
				300	
l ² t	I2t value	tp = 10 ms	450	A ² s	
dl/dt	Critical rate of rise of on-state current Gate supply: IG = 500mA dig/dt = 1A/µ	Repetitive F = 50 Hz	10	A/μs	
		Non Repetitive	50		
Tstg Tj	Storage and operating junction temperature range			- 40 to + 150 - 40 to + 125	°C °C
TI	Maximum lead temperature for soldering during 10 s at 4.5 mm from case			260	°C

Symbol	Parameter		BTA41A/B / BTB41 B			
		400	600	700	800	
V _{DRM} V _{RRM}	Repetitive peak off-state voltage Tj = 125 °C	400	600	700	800	V

March 1995 1/5

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit	
Rth (j-a)	Junction to ambient	50	°C/W	
Rth (j-c) DC	Junction to case for DC	DC BTA		°C/W
		втв	0.8	
Rth (j-c) AC	Junction to case for 360° conduction angle (F= 50 Hz)	вта	0.9	°C/W
	(F= 50 Hz)		0.6	

GATE CHARACTERISTICS (maximum values)

 $PG~(AV) = 1W~~PGM = 40W~(tp = 20~\mu s)~~IGM = 8A~(tp = 20~\mu s)~~V_{GM} = 16V~(tp = 20~\mu s).$

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions		Quadrant		Suffix		Unit
					Α	В	
IGT	V _D =12V (DC) R _L =33Ω	Tj=25°C	1-11-111	MAX	100	50	mA
			IV	MAX	150	100	
VGT	V _D =12V (DC) R _L =33Ω	Tj=25°C	I-II-III-IV	MAX	1.5		V
VGD	VD=VDRM RL=3.3kΩ	Tj=125°C	I-II-III-IV	MIN	0.	.2	V
tgt	$V_D=V_DRM$ $I_G=500mA$ $dI_G/dt=3A/\mu s$	Tj=25°C	I-II-III-IV	TYP	2.5		μs
IL	I _G =1.2 I _G T	Tj=25°C	I-III-IV	TYP	70	60	mA
			II		200	180	
IH *	I _T = 500mA gate open	Tj=25°C		MAX	100	80	mA
V _{TM} *	I _{TM} = 60A tp= 380μs	Tj=25°C		MAX	1.8		V
IDRM	V _{DRM} Rated	Tj=25°C		MAX	0.0	01	mA
IRRM	VRRM Rated	Tj=125°C		MAX	(6	
dV/dt *	Linear slope up to V _D =67%V _{DRM} gate open	Tj=125°C		MIN	250	250	V/μs
(dV/dt)c *	(dl/dt)c = 18A/ms BTA (dl/dt)c = 20A/ms BTB	Tj=125°C		MIN	10		V/μs

^{*} For either polarity of electrode A2 voltage with reference to electrode A1.

ORDERING INFORMATION

Package	IT(RMS)	V _{DRM} / V _{RRM}	Sensitivity :	Specification
	A	v	Α	В
BTA	41	400	Χ	X
(Insulated)		600	X	X
		700	Χ	X
		800	X	X
ВТВ	45	400		X
(Uninsulated)		600		X
		700		Х
		800		Х

Fig.1: Maximum RMS power dissipation versus RMS on-state current (F=50Hz).

(Curves are cut off by (dl/dt)c limitation) (BTA)

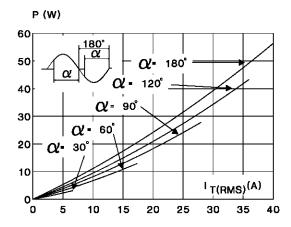


Fig.3: Maximum RMS power dissipation versus RMS on-state current (F=50Hz). (Curves are cut off by (dl/dt)c limitation) (BTB)

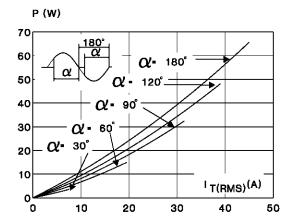


Fig.2: Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTA).

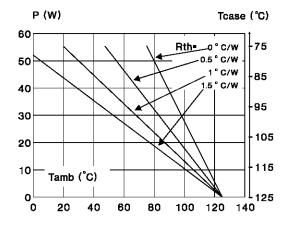


Fig.4: Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTB).

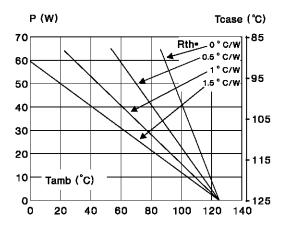


Fig.5: RMS on-state current versus case temperature. (BTA)

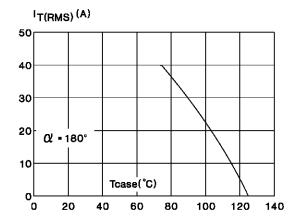


Fig.7: Relative variation of thermal transient impedance pulse duration.

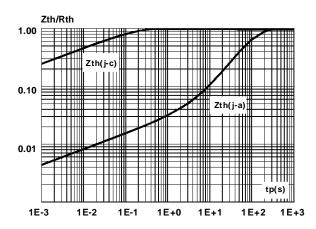


Fig.9 : Non Repetitive surge peak on-state current versus number of cycles.

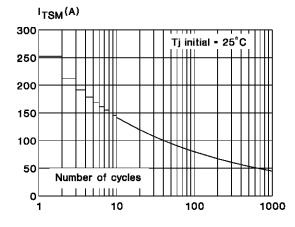


Fig.6: RMS on-state current versus case temperature. (BTB)

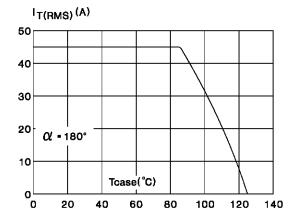


Fig.8 : Relative variation of gate trigger current and holding current versus junction temperature.

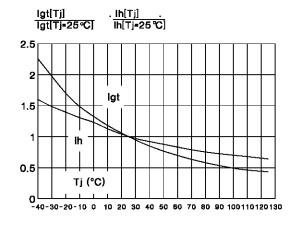


Fig.10: Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \le 10ms$, and corresponding value of l^2t .

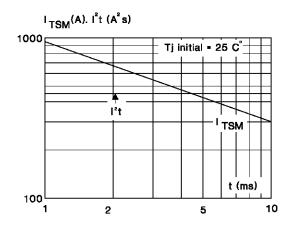
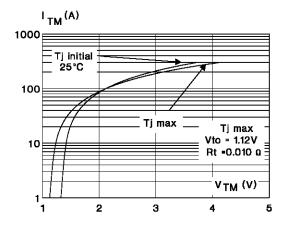
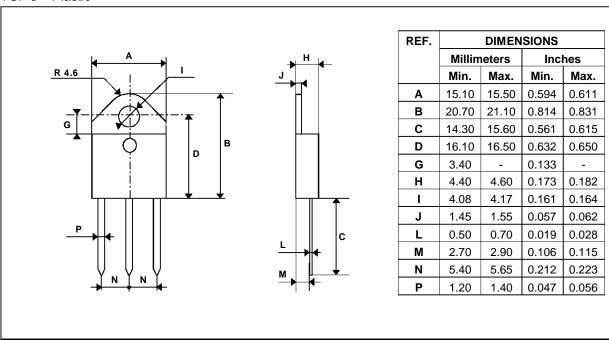


Fig.11: On-state characteristics (maximum values).



PACKAGE MECHANICAL DATA

TOP 3 Plastic



Cooling method: C Marking: type number

Weight: 4.7 g

Recommended torque value : 0.8 m.N. Maximum torqur value : 1 m.N.

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